ABSTRACT

METHOD FOR SOLDER BUMPING, AND SOLDER-BUMPING STRUCTURES PRODUCED THEREBY

A method for solder bumping provides a substrate and forms a film on the substrate. The film has openings therethrough. A stencil is aligned on the film. The stencil has openings therethrough over the openings through the film. Solder paste is printed onto the substrate and into the openings through the stencil and the openings through the film. The solder paste is reflowed to form solder balls therefrom. The stencil and the film are then removed. (Fig. 8)